IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIES	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Form Type <sup>3</sup> Distribute	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mi	ials and Mfg Information			
upplier Inform	nation													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2025-06-05				
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			1	NA NA				Product-Env-Stewards@onsemi.com			
uthorized Represe	entative*	Title - Representative			F	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com			
Requeste	er Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Manufacturing Site	7	Veight*	UOM	Unit Type
	ES3B		UFR SMC PN 3A 100V			2025-06-05		7	TSCBE		32.5	mg	Each	
	Process Information		arminal Desa	Alloy	STD-020 MSL	Pating	Dook Proc	ng Pody T	'amnorot	May Time at Peak	Tomporet	uro Numb	per of Reflow Cyc	alac
5 - 1			Terminal Base Alloy J-ST CU Alloy 1		S I D-020 MSL	Kating	260	ess Body 1	ss Body Temperature   Max Time at Peak   C   30		seconds 3		ber of Kellow Cyc	cies
•	n (Sn) - anneated	C	U Alloy	1			200		<u>lc</u>	30	second	18 3		
omments	ime of peak townst	duning1	domina ia 10-2	0 seconds										
	ime at peak temperature													
more information	on regarding material co	mposition p	piease refer to	page 3										

<b>RoHS Material Composition Declaration</b>			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for tum (Cr6+), Polybrominated Biphenyls (PBB), Polyl Disobutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that arise regarding information the Supplier provides in this f										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).  Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature R		,								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.798	mg	A	Lead (Pb)	7439-92-1	7c	0.1823	mg
			Supplier	Silicon (Si)	7440-21-3		3.5625	mg
			В	Nickel (Ni)	7440-02-0		0.0342	mg
			Supplier	Gold (Au)	7440-57-5		0.019	mg
Die Attach Solder	4.36	mg	Supplier	Silver (Ag)	7440-22-4		0.109	mg
			A	Lead (Pb)	7439-92-1	7a	4.033	mg
			Supplier	Tin (Sn)	7440-31-5		0.218	mg
Lead Frame	90.9231	mg	Supplier	Iron (Fe)	7439-89-6		0.1091	mg
			Supplier	Copper (Cu)	7440-50-8		90.7867	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0273	mg
Mold Compound-Black	132.0	mg		Metal Hydroxide	proprietary data		4.62	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		10.56	mg
			Supplier	Carbon Black (C)	1333-86-4		0.66	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		105.6	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		10.56	mg
Plating	1.4189	mg	Supplier	Tin (Sn)	7440-31-5		1.4189	mg